

Technical Data  
 Data Sheet N0079, Rev. A

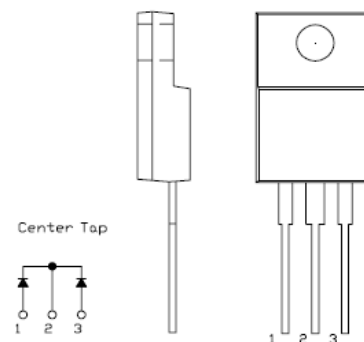
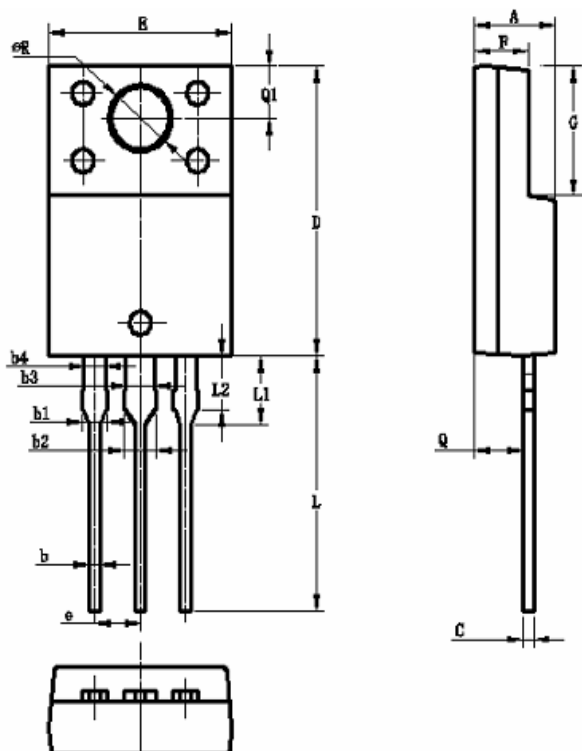
## MBRF10200CT SCHOTTKY RECTIFIER

**Applications:**

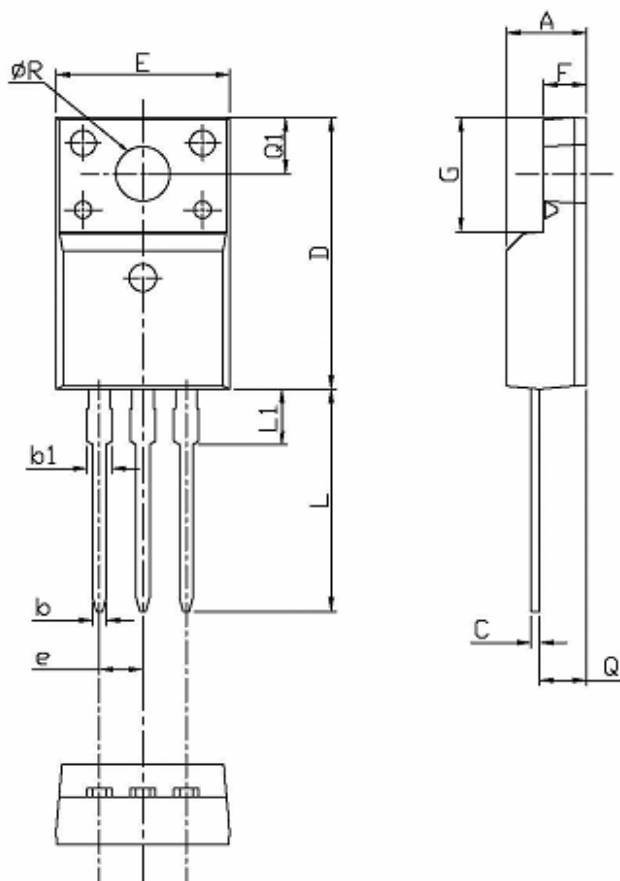
- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

**Features:**

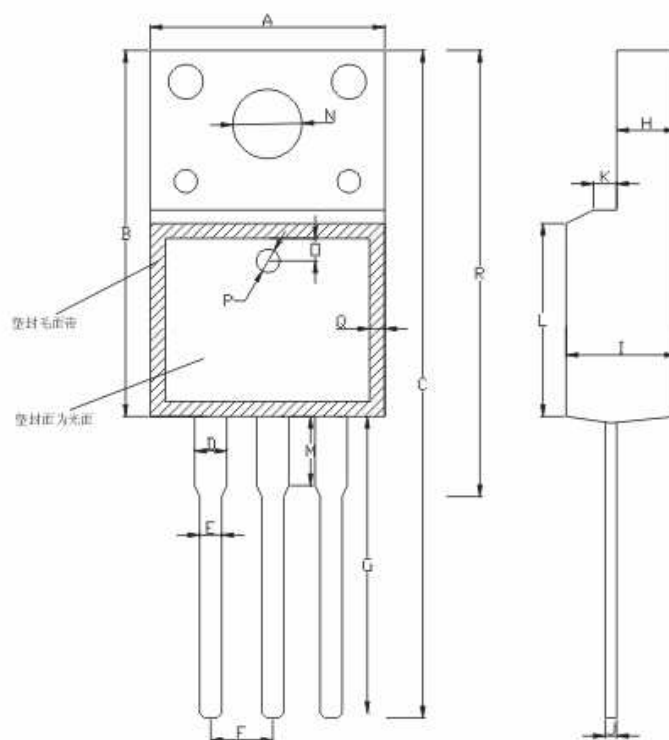
- 150°C T<sub>J</sub> operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request


**OUTLINE DRAWING**
**Mechanical Dimensions: In mm / Inches**


Dim	OPTION 1(CJ)		OPTION 2(HD)	
	Min	Max	Min	Max
A	4.35	4.65	4.30	4.70
b	0.50	0.75	0.50	0.75
b1	1.15	1.402	1.20	1.45
b2	1.55	1.802	1.60	1.85
b3	1.55	1.65	1.50	1.75
b4	1.10	1.35	1.10	1.35
C	0.50	0.75	0.55	0.75
D	14.8	15.2	14.80	15.20
E	10.06	10.26	9.96	10.36
e	2.46	2.62	2.55TYP	
F	2.85	3.15	2.80	3.20
G	6.50	6.90	6.50	6.90
L	12.70	13.70	12.70	13.70
L1	3.40	3.80	3.40	4.00
L2	2.60	3.00	-	-
Q	2.60	2.80	2.50	2.90
Q1	2.50	2.90	2.50	2.90
ØR	3.40	3.60	3.30	3.70



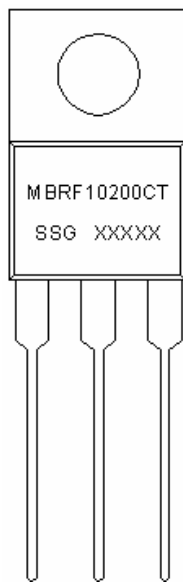
Dim	OPTION 3		OPTION 4	
	Min	Max	Min	Max
A	4.53	4.93	4.50	4.90
b	0.71	0.91	0.70	0.90
b1	1.15	1.39	1.33	1.47
C	0.36	0.53	0.45	0.60
D	15.67	16.07	15.67	16.07
E	9.96	10.36	9.96	10.36
e	2.54 TYP		2.54 BSC	
F	2.34	2.76	2.34	2.74
G	6.50	6.90	6.48	6.88
L	12.37	12.77	12.78	13.18
L1	2.23	2.63	3.03	3.43
Q	2.56	2.96	2.56	2.96
Q1	3.10	3.50	3.10	3.50
$\varnothing R$	2.98	3.38	3.08	3.28



A:10.20 ± 0.50	B:15.90 ± 0.50	C:29.00 ± 1.00	D:1.24 ± 0.10
E:0.80 ± 0.10	F:2.54 ± 0.10	G:13.10 ± 1,0	H:2.55 ± 0.05
I:4.70 ± 0.05	J:0.50 ± 0.05	K:1.20 ± 0.20	L:8.00 ± 0.50
M:3.00 ± 0.50	N:3.20 ± 0.20	O:1,25 ± 0.05	P:1.5 ± 0.05
Q:1.0 ± 0.20	R:19.2 ± 1.0		

**OPTION 5(SR)**

**ITO-220AB**

**Marking Diagram:**


Where XXXXX is YYWWL

MBR	= Device Type
F	= Package type
10	= Forward Current (10A)
200	= Reverse Voltage (200V)
CT	= Configuration
SSG	= SSG
YY	= Year
WW	= Week
L	= Lot Number

**Cautions:** Molding resin  
 Epoxy resin UL:94V-0

**Ordering Information:**

Device	Package	Shipping
MBRF10200CT	ITO-220AB (Pb-Free)	50pcs / tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

**Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	$V_{RWM}$	-	200	V
Max. Average Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_C = 105^\circ\text{C}$ rectangular wave form	10	A
Max. Peak One Cycle Non-Repetitive Surge Current (per leg)	$I_{FSM}$	8.3 ms, half Sine pulse	128	A

**Electrical Characteristics:**

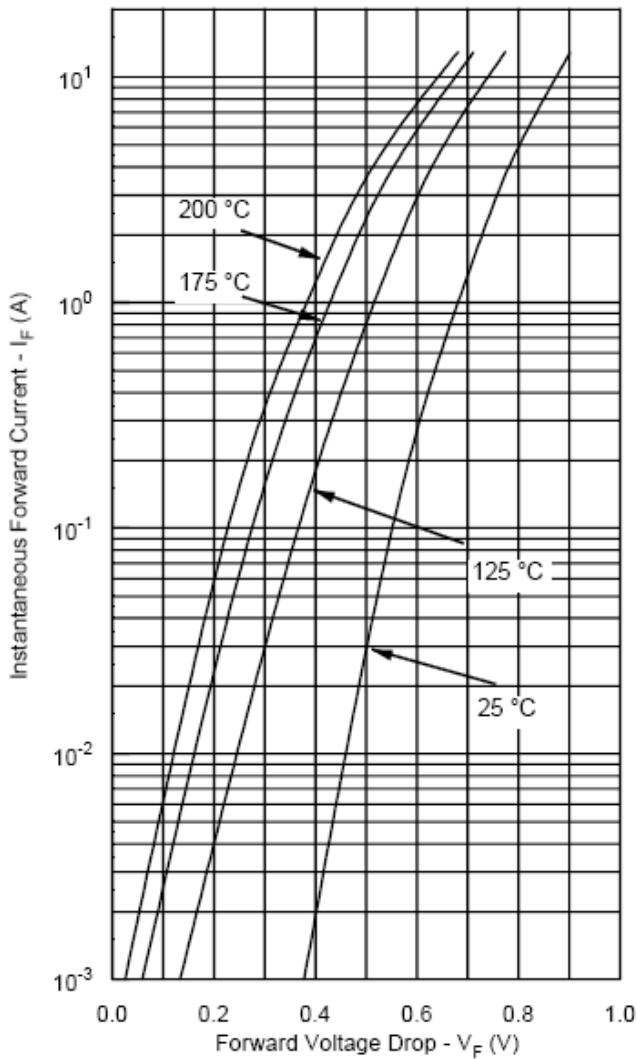
Characteristics	Symbol	Condition	Max.	Units
Max. Forward Voltage Drop (per leg) *	$V_{F1}$	@ 5A, Pulse, $T_J = 25\text{ }^\circ\text{C}$	0.98	V
	$V_{F2}$	@ 5A, Pulse, $T_J = 125\text{ }^\circ\text{C}$	0.78	V
Max. Reverse Current at DC condition (per leg)	$I_{R1}$	@ $V_R = \text{rated } V_R$ $T_J = 25\text{ }^\circ\text{C}$	1.0	mA
Max. Reverse Current (per leg) *	$I_{R2}$	@ $V_R = \text{rated } V_R$ $T_J = 125\text{ }^\circ\text{C}$	7	mA
Max. Junction Capacitance (per leg)	$C_T$	@ $V_R = 5\text{V}$ , $T_C = 25\text{ }^\circ\text{C}$ $f_{SIG} = 1\text{MHz}$	150	pF
Typical Series Inductance (per leg)	$L_S$	Measured lead to lead 5 mm from package body	8.0	nH
Max. Voltage Rate of Change	dv/dt	-	10,000	V/ $\mu\text{s}$
RSM Isolation Voltage (t = 1.0 second, R. H. <=30%, $T_A = 25\text{ }^\circ\text{C}$ )	$V_{ISO}$	Clip mounting, the epoxy body away from the heatsink edge by more than 0.110" along the lead direction.	4500	V
		Clip mounting, the epoxy body is inside the heatsink.	3500	
		Screw mounting, the epoxy body is inside the heatsink.	1500	

\* Pulse Width < 300 $\mu\text{s}$ , Duty Cycle < 2%

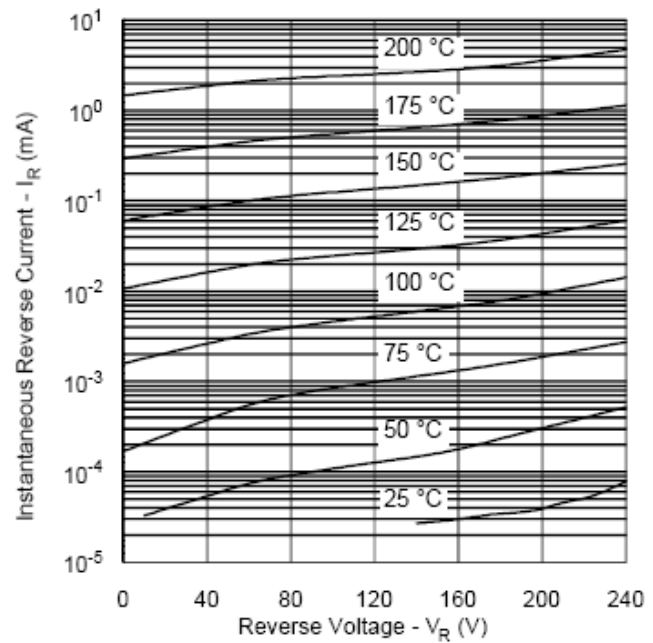
**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Max. Junction Temperature	$T_J$	-	-55 to +150	$^\circ\text{C}$
Max. Storage Temperature	$T_{stg}$	-	-55 to +150	$^\circ\text{C}$
Maximum Thermal Resistance Junction to Case (per leg)	$R_{\theta JC}$	DC operation	4.5	$^\circ\text{C/W}$
Approximate Weight	wt	-	2	g
Case Style	ITO-220AB			

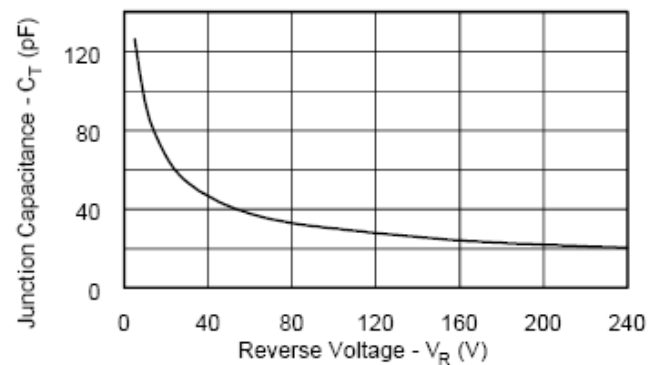
**Typical Forward Characteristics**



**Typical Reverse Characteristics**



**Typical Junction Capacitance**



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